

A-C® Polymers for Metallocene Hot Melt Adhesives

Honeywell A-C® low-molecular-weight polymers help boost the adhesion performance of metallocene-based hot melt adhesives, particularly in packaging applications.



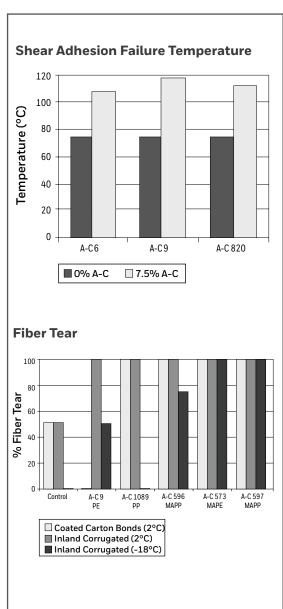
Increased Heat Resistance

Adhesive performance at high temperatures is critical to ensuring that the quality of the packaging does not degrade over its useful life. The graph shows a significant increase in shear adhesion failure temperature when A-C polymers are added to metallocene hot melt adhesives.

Test Composition (%)	Control	A-C®	
A-C Low MWPE	0	7.5	
HC Tackifier	30	30	
Metallocene polymer	40	40	
FT Wax	30	22.5	

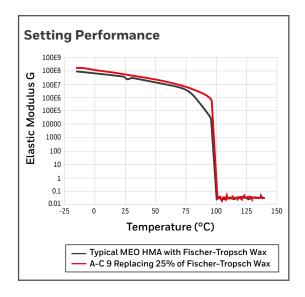
Increased Adhesion

Adding A-C polymers to metallocene hot melt adhesives will result in increased fiber tear on coated cardboard in packaging applications, even under refrigerator and freezer temperatures.



Reduced Set Time

Adding A-C® performance polymers to metallocene hot melt adhesive formulations will reduce the set time. Generally, Fischer-Tropsch waxes are used to achieve reduced set times. Using A-C polymers with or without Fischer-Tropsch waxes will provide reduced set times, as well as the additional benefits of increased adhesion and heat resistance.



Ту	ре	Benefits	Drop Point (°C)	Hardness (dmm)	Density	Viscosity at 140 °C (cps)
A-C 6	Homopolymer PE	Reduced set time and increased heat resistance	106	4	0.92	375
A-C 9			115	0.5	0.93	450
A-C 820			126	<0.5	0.96	80
A-C 573P	Maleated PE	Increased adhesion	106	4.5	0.92	600
A-C 596P	Maleated PP	Increased adhesion and increased heat resistance	141	<0.5	0.93	150(190°C)
A-C 597P	Maleated PP		141	<0.5	0.94	350 (190°C)

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